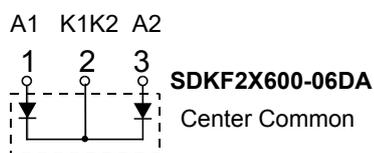
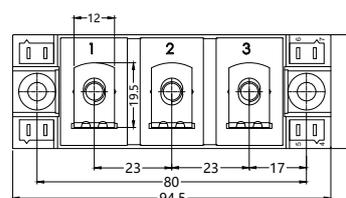
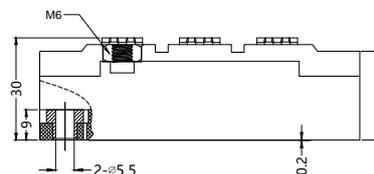


# SDKF2X600-06DA

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules



### Dimensions in mm



	$V_{RSM}$ V	$V_{RRM}$ V
SDKF2X600-06DA	600	600

Symbol	Test Conditions	Maximum Ratings	Unit
$I_{FRMS}$	$T_C=75^{\circ}C$	860	A
$I_{FAVM}$	$T_C=75^{\circ}C$ ; rectangular, $d=0.5$ per chip	600	
$I_{FRM}$	$t_p < 10\mu s$ ; rep. rating, pulse width limited by $T_{VJM}$	3500	
$I_{FSM}$	$T_{VJ}=45^{\circ}C$ $t=10ms$ (50Hz), sine $t=8.3ms$ (60Hz), sine	3800 4100	A
	$T_{VJ}=150^{\circ}C$ $t=10ms$ (50Hz), sine $t=8.3ms$ (60Hz), sine	3420 3900	
$I^2t$	$T_{VJ}=45^{\circ}C$ $t=10ms$ (50Hz), sine $t=8.3ms$ (60Hz), sine	47000 47300	$A^2s$
	$T_{VJ}=150^{\circ}C$ $t=10ms$ (50Hz), sine $t=8.3ms$ (60Hz), sine	38100 39000	
$T_{VJ}$ $T_{stg}$ $T_{Smax}$		-40...+150 -40...+125 110	$^{\circ}C$
$P_{tot}$	$T_C=25^{\circ}C$	1050	W
$V_{ISOL}$	50/60Hz, RMS $t=1min$	3000	V~
	$I_{ISOL} \leq 1mA$ $t=1s$	3600	
$M_d$	Mounting torque (M6)	2.25-2.75/20-25	Nm/lb.in.
	Terminal connection torque (M6)	4.50-5.50/40-48	
$d_s$	Creeping distance on surface	12.7	mm
$d_A$	Strike distance through air	9.6	mm
$a$	Maximum allowable acceleration	50	$m/s^2$
Weight		150	g



# SDKF2X600-06DA

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
<b>I<sub>R</sub></b>	T <sub>VJ</sub> =25°C; V <sub>R</sub> =V <sub>RRM</sub>		10	mA
	T <sub>VJ</sub> =25°C; V <sub>R</sub> =0.8·V <sub>RRM</sub>		5	
	T <sub>VJ</sub> =125°C; V <sub>R</sub> =0.8·V <sub>RRM</sub>		80	
<b>V<sub>F</sub></b>	I <sub>F</sub> =300A; T <sub>VJ</sub> =25°C	1.20	1.30	V
	I <sub>F</sub> =450A; T <sub>VJ</sub> =25°C	1.27	1.37	
	I <sub>F</sub> =500A; T <sub>VJ</sub> =25°C	1.29	1.39	
	I <sub>F</sub> =600A; T <sub>VJ</sub> =25°C	1.38	1.48	
	I <sub>F</sub> =1200A; T <sub>VJ</sub> =25°C	1.70	1.80	
<b>V<sub>TO</sub></b>	For power-loss calculations only		0.88	V
<b>r<sub>T</sub></b>			1.47	mΩ
<b>R<sub>thJH</sub></b>	DC current		0.102	K/W
<b>R<sub>thJC</sub></b>	DC current		0.067	
<b>t<sub>rr</sub></b>	I <sub>F</sub> =600A; T <sub>VJ</sub> =100°C	320	450	ns
<b>I<sub>RM</sub></b>	V <sub>R</sub> =300V; T <sub>VJ</sub> =25°C		80	A
	-di/dt=400A/us; T <sub>VJ</sub> =100°C		90	A

### FEATURES

- \* International standard package
- \* Planar passivated chips
- \* Short recovery time
- \* Low switching losses
- \* Soft recovery behaviour
- \* Isolation voltage 3600 V~
- \* DCB baseplate
- \* RoHS compliant

### APPLICATIONS

- \* Antiparallel diode for high frequency switching devices
- \* Free wheeling diode in converters and motor control circuits
- \* Inductive heating and melting
- \* Uninterruptible power supplies (UPS)
- \* Ultrasonic cleaners and welders

### ADVANTAGES

- \* High reliability circuit operation
- \* Low voltage peaks for reduced protection circuits
- \* Low noise switching
- \* Low losses

# SDKF2X600-06DA

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

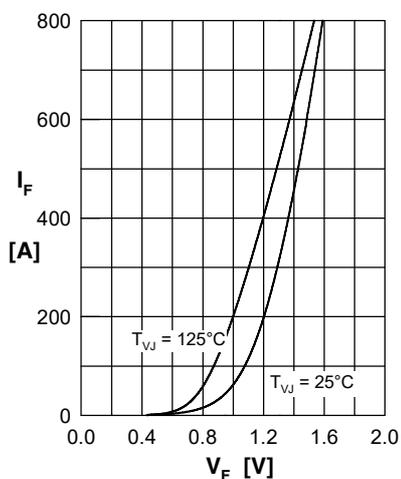


Fig. 1 Typ. forward current  $I_F$  vs voltage drop  $V_F$  per leg

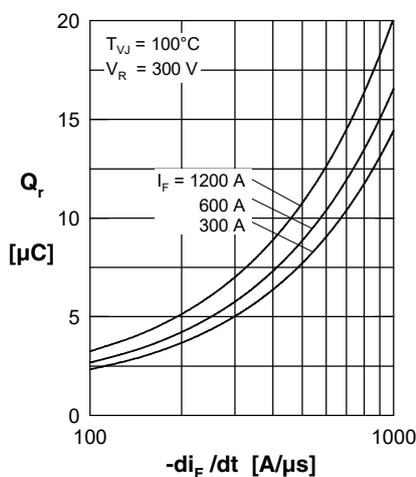


Fig. 2 Typ. reverse recovery charge  $Q_r$  versus  $-di_F/dt$

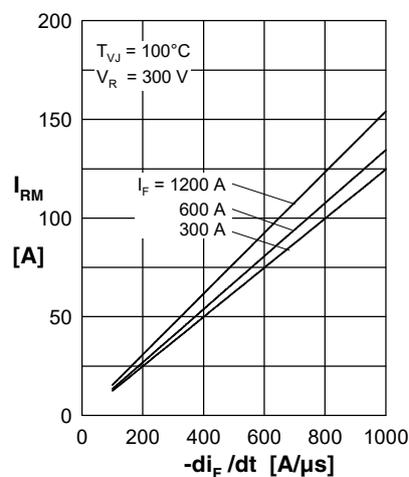


Fig. 3 Typ. peak reverse current  $I_{RM}$  versus  $-di_F/dt$

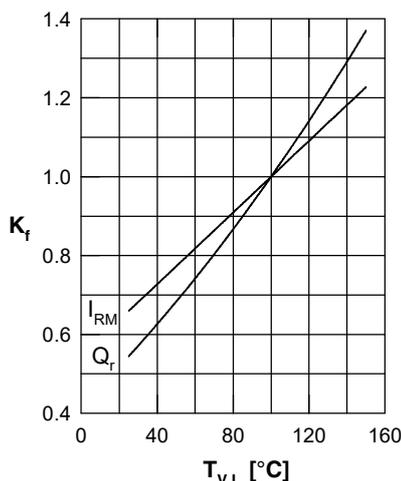


Fig. 4 Typ. dynamic parameters  $Q_r$ ,  $I_{RM}$  vs. junction temperature  $T_{VJ}$

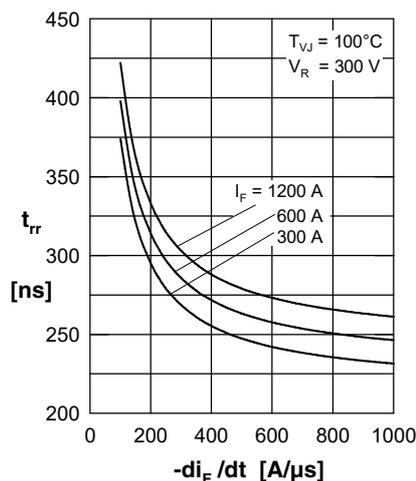


Fig. 5 Typ. recovery time  $t_{tr}$  versus  $-di_F/dt$

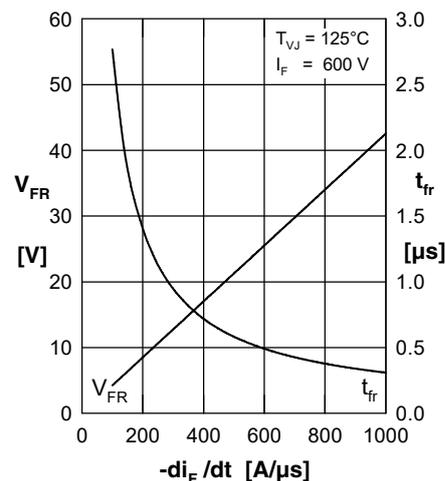


Fig. 6 Typ. peak forward voltage  $V_{FR}$  and  $t_{fr}$  versus  $-di_F/dt$

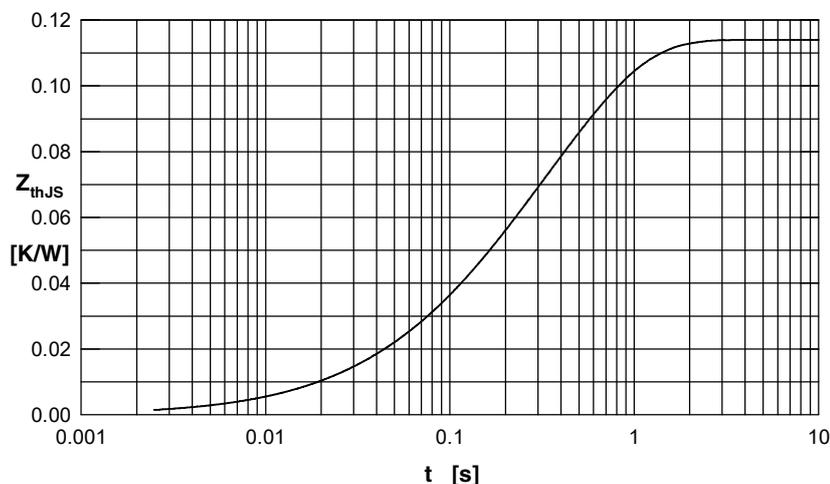


Fig. 7 Typ. transient thermal impedance junction to heatsink

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.001	0.080
2	0.004	0.024
3	0.027	0.112
4	0.082	0.464